

**3D Solder Paste Inspection Machine** 



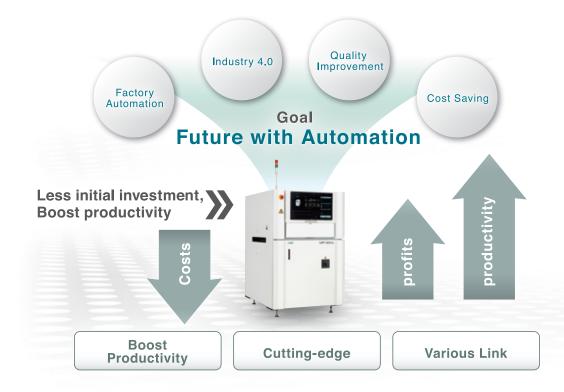
# "Achieve Your Goals with CKD" Most Reliable Quality Assurance

- ➤ Cutting-edge Technologies
- **▶** Boost Productivity
- ▶ Various Link Functions





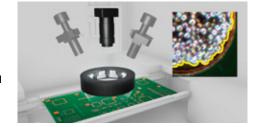
# "Achieve Your Goals with CKD"



# **Cutting-edge Technologies**

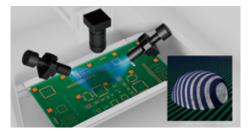
## **Ring Light**

An outline of solder paste is extracted through the use of a 360° ring light source that projects against inspection objects (solder paste). This method of inspection isolates solder paste on a Printed Circuit Board (PCB) and performs three-dimensional measurements to achieve more reliable inspections.



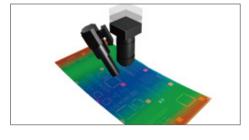
## **3D Projectors**

A camera captures solder paste images with a stripe pattern light using 3D projectors that are positioned diagonally and faced downwards. Depending on the height of the solder paste, the stripe pattern light will shift according to the relative height. Through the principles of triangulation, the height is calculated based on the stripe pattern light shift.



### Z axis Auto-Focus Function

The amount of PCB warping is measured in each field of view and the inspection camera automatically compensates for the distance between the camera and the surface of the PCB. This function enables users to perform inspections without the influence of PCB warping.

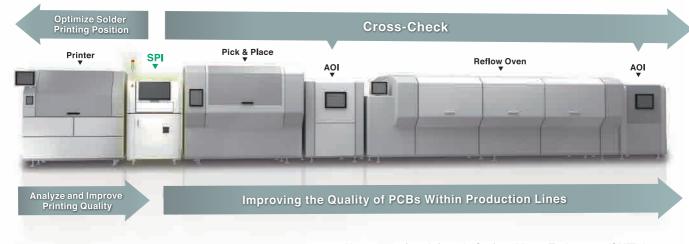




# **Various Link Functions**

# **Smart SMT Style**

Solder paste inspection machines (SPI) can analyze and optimize printing conditions.



70%

About 70% of all defects in Surface Mount Technology (SMT) lines are said to occur in the printing process.

The VP-01G prevents printing defects by detecting faults and optimizing printing conditions.

# For Factory Automation

# 1 Auto Program Launch

Contribute to a significant increase in operating rate

# 2 Closed Loop

Improve quality in cooperation with previous and next machines

# 3 Bad Mark Communication

Share defect information and reduce loss cost

### 4 AOI Link

Narrow down the true cause of defects by cross-check

# For Quality & Productivity

# 1 SPC

Help the improvement of quality by analyzing the trend of production status

# 2 X-bar R / X-bar S Display

Visualize the production status in real time

# 3 Line Quality Management

Prevent the outflow of defective products by process control using X-bar and CP/CPK

# **4** Log Information Output

The output file can be used for the function of linking with external applications.

# **Boost Productivity**

A Wide Variety of Requests in PCB Inspection

# Foreign Material

Solder paste scatter, PCB cut dust, thread waste and cleaning paper dust ar occurred on PCB.



# PCB Color

Produce a wide variety o PCB. Inspection is not stable due to the colo of the PCB



## Glue

3D Inspection for glue is desirable as the amount of applied glue is not stable



#### **PCB** Warpage

Printing is not stable du



## Flexible PCB

on flexible PCB needs
to be inspected accuratel



### **Mixed-size Parts**

Inspection time becomes long when selecting the machine model in



# High-density Mounting PCB

high-density mounting PCB



# All Satisfied by the Function of VP-01G



V2-016

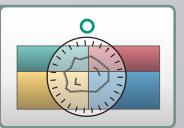
**VP-01**G

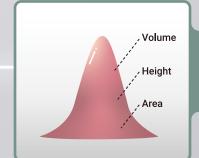
# **Foreign Material**

The presence or absence of foreign materials can be detected while simultaneously inspecting the solder paste.

#### **PCB Color**

CKD's unique RGB light source system enables stable inspection regardless of the PCB color.



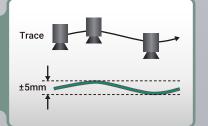


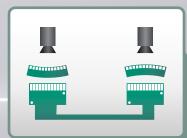
#### Glue

The amount of applied glue can be measured stably in 3D.

# **PCB** Warpage

Board warpage up to ±5 mm is supported and inspected stably.



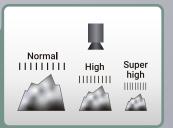


#### Flexible PCB

The inspection camera can follow and inspect the wavy PCB which is peculiar to flexible PCB.

#### **Mixed-size Parts**

High productivity can be achieved with optimal inspection and measurement by using multi-resolution switching function for large and small mixed-mounting parts





## **High-density Mounting PCB**

Inspection speed has been improved for high-density mounting PCB with large number of pads, compared to older models. In addition, new 10um/5um resolution setting has been added to the lineup in order to support fine parts.

#### **Standard Specifications**

| Standard S                  | pecifications   |  |                 |                 |                 |
|-----------------------------|---|--|-----------------|-----------------|-----------------|
| Basic<br>Specification      | Dimensions (W x D x H)                                      | 938 × 1,191 × 1,480mm  |                 |                 |                 |
|                             | Conveyor Height   | 900 ±20mm  |                 |                 |                 |
|                             | PCB Size  | 50 x 50 - 510 x 510mm (L size)   |                 |                 |                 |
|                             | Min. PCB Edge Clearance                                     | 4 mm   |                 |                 |                 |
|                             | PCB Clearance (Top/Bottom)                                  | Top 5mm, Bottom 30mm   |                 |                 |                 |
|                             | PCB Thickness   | 0.3 - 5.0mm  |                 |                 |                 |
|                             | PCB Weight  | Less than 5kg  |                 |                 |                 |
|                             | Machine Weight  | 600kg  |                 |                 |                 |
|                             | Power Supply  | Single phase AC200V - 240V ±10% 50/60Hz ±1Hz   |                 |                 |                 |
|                             | Power consumption   | Max. 1KVA  |                 |                 |                 |
|                             | Pneumatic Supply  | 0.3 - 0.4Mpa (4kgf/cm²)  |                 |                 |                 |
| VP Inspection<br>Technology | Camera  | CMOS Mono Camera -Global shutter spec  |                 |                 |                 |
|                             | Inspection Principle  | Phase Shift + Hybrid Inspection - 2D Ring light and 3D Projector(s)  |                 |                 |                 |
|                             | Inspection Item   | Volume, Projection, Dimness, Area, Shift, Average Height, Bridging,<br>No Solder, Coplanarity, Foreign Material, Glue (Option) |                 |                 |                 |
|                             | Clamping Method   | Side, Top and Bottom Simultaneous Clamping   |                 |                 |                 |
| Mechanical                  | PCB Stop  | Sensor Control System (No Stopper)   |                 |                 |                 |
| Technology                  | PCB Load/Transfer   | Double Side PCB Loading/Transfer System  |                 |                 |                 |
|                             | PCB Warpage   | ±5mm (Original Mechanical Adjustment System)   |                 |                 |                 |
| Performance                 | Inspection Resolution (Multiple Resolution Switch Function) | 25/12.5/8.5µm  | 20/10/7µm       | 15/7.5/5μm      | 10/5μm          |
|                             | Solder Paste Height (Standard)                              | Less than 400µm  | Less than 300µm | Less than 300µm | Less than 150µm |
|                             | Solder Paste Height (Option)                                | Less than 600µm  | Less than 450µm | Less than 450µm | Less than 225µm |
|                             | Max. Inspection Speed                                       | 9400mm²/sec  | 6000mm²/sec     | 3300mm²/sec     | 1400mm²/sec     |
|                             | FOV Size  | 50 x 50mm  | 40 x 40mm       | 30 x 30mm       | 20 x 20mm       |
|                             | Min. Solder Paste Pitch                                     | 50µm (Stencil thickness: 100um)  |                 |                 |                 |
|                             | Height Resolution   | 1µm  |                 |                 |                 |
|                             | Accuracy (3σ)   | Within 2% (Dual Projection)/Within 3% (Single Projection)  |                 |                 |                 |
|                             | GR & R  | Within 10%   |                 |                 |                 |
| Software                    | Inspection Program  | CKD VPDS Programing System (Program Creation Time Min. 3 mins) ePM Programing Software (Option)                                |                 |                 |                 |
|                             | SPC   | CKD Realdata Software System (Real Time Histogram, X bar & R Chart, CP/CPK Chart, Real Time SPC, SPC Alarm, SPC Report)        |                 |                 |                 |
| Optional                    | Closed Loop   |  |                 |                 |                 |
|                             | ePM   | Over view  | W               |                 |                 |
|                             | Auto Program Launch   |  |                 |                 | <b>†</b>        |
|                             | Area Standard Jig   |  |                 |                 |                 |
|                             | Height Standard Jig   | • 1  | Q 27(2)         |                 | 11              |
|                             | ITAC  |  |                 |                 |                 |
|                             | Q-up Opti   | 1  | MA SEA          | 0               | 30              |
|                             | Dual Projection   | 1  | in .            |                 | 1480            |



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CE Compliance